

AMENDMENTS TO THE CLAIMS

1-6. (Cancelled)

7. (Previously Presented) A method of plating a substrate with copper, comprising:

bringing a substrate into contact with a processing liquid offering surface activity of a surface of the substrate and/or increasing wettability between a plating solution and the surface of the substrate;

performing at least one of removing the processing liquid from the substrate and drying the substrate; and

bringing the substrate into contact with the plating solution to plate the substrate after performing said at least one of removing the processing liquid from the substrate and drying the substrate;

wherein said bringing the substrate into contact with the processing liquid and said bringing the substrate into contact with the plating solution are performed, respectively, in separated units arranged in the same horizontal plane.

8. (Previously Presented) A method according to claim 7, wherein said performing at least one of removing the processing liquid from the substrate and drying the substrate includes one of rotating the substrate to spin off the processing liquid from the substrate, rotating the substrate and applying a gas blow to the substrate, and passing the substrate through forced air.

9. (Previously Presented) A method according to claim 7, wherein said performing at least one of removing the processing liquid from the substrate and drying the substrate comprises successively removing the processing liquid from the substrate and drying the substrate using only one apparatus after the substrate is brought into contact with the processing liquid.

10-12. (Cancelled)

13. (Previously Presented) A method according to claim 7, wherein said bringing the substrate into contact with the processing liquid comprises repeatedly bringing the substrate into contact with the processing liquid.

14. (Previously Presented) A method according to claim 7, wherein said bringing the substrate into contact with the processing liquid comprises bringing the substrate into contact with a processing liquid containing at least one of an organic substance and a sulfur compound.

15. (Cancelled)